Refill Solders

Lead-free alloys for electronics

PRODUCT DESCRIPTION

Stannol refill solder alloys are copper-free versions of lead-free alloys. These are used to reduce increased copper content in solder baths. These versions can be used in wave or selective soldering systems as well as in immersion baths. FLOWTIN refill alloys ensure that the used micro alloying additions will remain in the required range and are not diluted. Thus the solder bath content completely remains the full FLOWTIN properties. Refill solders with silver content can be used to reduce copper and at the same time keep the silver content stable.

PRODUCT FEATURES

Different compositions – suitable for the original alloy

- **Refill alloys are miscible in any ratio with the corresponding original alloy**
- **For correcting the composition of solder baths**
- **To reduce the content of process-related impurities, especially copper**

APPLICATION

If copper or other alloying elements are no longer within the recommended or specified range of application, an increased number of solder defects may occur. These values can be determined by regular solder bath analysis. The Stannol analysis service carries out solder bath analyses and helps with recommendations to correct the composition.

REFILL ALLOY		ORIGINAL ALLOY	
Name	**Composition**	**Name**	**Composition**
Flowtin TS 380*	Sn96.2Ag3.8	**Flowtin TSC 385***	Sn95.7Ag3.8Cu0.5
Flowtin TS 300*	Sn97.0Ag3.0	**Flowtin TSC 305***	Sn96.5Ag3.0Cu0.5
Flowtin TS 260*	Sn97.4Ag2.6	**Flowtin TSC 263***	Sn97.1Ag2.6Cu0.3
Flowtin TS 03*	Sn99.7Ag0.3	**Flowtin TSC 0307*.**	Sn99Cu0.7Ag0.3
Flowtin TS 08*	Sn99.2Ag0.8	**Flowtin TSC 0807***	Sn98.5Ag0.8Cu0.7
Flowtin T*	Sn99.9	**Flowtin TC***	Sn99.3Cu0.7
Ecoloy TS 03	Sn99.7Ag0.3	**Ecoloy TSC 0307**	S-Sn99Cu0.7Ag0.3
Ecoloy TS380	Sn96,2Ag3,8	**Ecoloy TSC**	Sn95,5Ag3,8Cu0,7
SN100Ce*.	Sn99.9	**SN100C*.**	Sn99.3Cu0.7
SN100CLe*	Sn99,9	**SN100CL***	Sn99,3Cu0,7
SN100CeS*	Sn99,9	**SN100CS***	Sn99,3Cu0,7
SN100CeS+*	Sn99,9	**SN100CS+***	Sn99,3Cu0,7
SN100CVe*	Sn98,5Bi1,5	**SN100CV***	Sn97,8Bi1,5Cu0,7
SN100C04-S*	Sn99,9	**SN100C07-S***	Sn99,3Cu0,7

* According to DIN EN ISO 9453 or internal specifications, additionally doped with micro alloy additives <0.1%.

RECOMMENDED APPLICATIONS

Wherever the composition of solders needs to be corrected. Mainly for reduction of copper contents to maintain proper soldering results at lowest possible solder temperatures.

DELIVERY FORM

- solid solder wire
- triangular bars
- Kg-bars
- ingots with hanging hole

HEALTH AND SAFETY

Read the material safety data sheet carefully before use and observe the safety precautions described.

DISCLAIMER